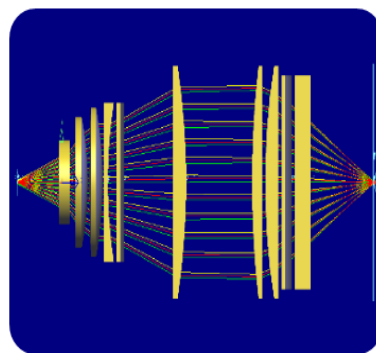
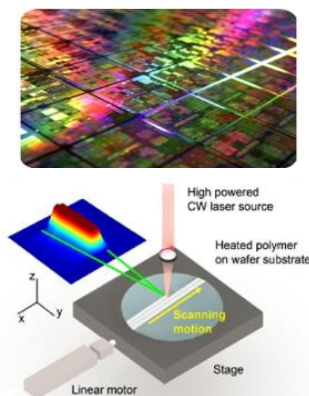


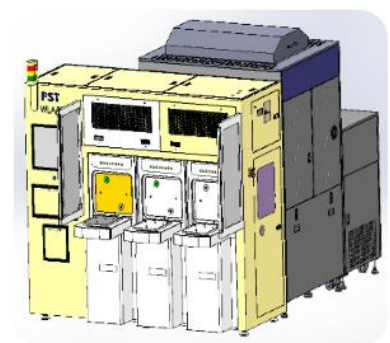
## Rapid Thermal Process The Local Laser Annealing System

for Semiconductor/FPD/PCB/etc.

- ❑ The Local Laser Annealing system series, High-power laser beam is using for the local heat treatment of various thin films in response to multiple applications.
- ❑ The laser beam energy distribution to the desired shape (square, rectangle, circle, etc.) or with laser beam forming technology.
- ❑ High throughput with precision stage for the R&D and manufacturing.



Optical design



Local Laser Annealing System

### Features

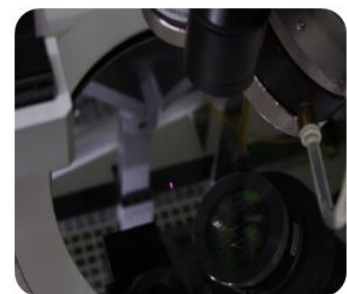
- Laser optical designs
- Laser uniformity <5%.
- Top hat beam and edge steepness <20 $\mu$ m per side.
- Output feedback control of wafer temperature measurement with laser condition.

### Applications

- WLA (Wafer/substrate local laser anneal)
- Local area pattern correction
- Local transistor repair (Vt adjustment or fuse repair)
- FPD: Local solder reflow process, laser (Flexible display)
- Local bonding/debonding for the adhesive film
- Wafer/substrate laser marking

### System Monitoring

- Depth measurement system for wafer/substrate
- Real time laser power monitoring (shot to shot monitoring)
- Laser beam profiler & check the CCD image for uniformity
- Wafer/substrate flatness measurement system
- Wafer/substrate temperature monitoring system



Local area laser annealing process